



Sheet 1 of 1

FORM PTO 1449 (modified)

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

LIST OF REFERENCES CITED BY APPLICANT(S)
(Use several sheets if necessary)

Date Submitted to PTO: April 11, 2003

ATTY DOCKET NO.: P67440US0

SERIAL NO.: 10/019,299

APPLICANT: Johshi GOTOH et al.

FILING DATE: March 11, 2002

GROUP: 2827

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
JHR	JP2000-220481	01-21-2000	JAPAN			X

OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER

James H. Alde

DATE CONSIDERED

5/5/03

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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Sheet 1 of 1

FORM PDS 1449 (modified)

ATTY DOCKET NO.:

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P67440US0

10/019,299

APPLICANT: Johshi GOTOH et al.

FILING DATE: January 7, 2002

GROUP: Unassigned

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
JHA	5,061,776	10/1991	WEAVER et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
JHA	JP2713760-B	09/1990	JAPAN (English Abstract)			
JHA	JP2738487-B	06/1994	JAPAN (English Abstract)			
JHA	JP10204259-A	08/1998	JAPAN (English Abstract)			
JHA	WO 98/31738	01/1998	PCT			
JHA	EP 0757067A1	03/1995	EUROPEAN			

OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)

JHA	"Solder Joint Life Improvement Using Adhesive Under Component", Research Disclosure - 2244 - (January, 1990) No. 309, New York, US - XP 000099320

EXAMINER

DATE CONSIDERED

5/5/03

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